

Dual Full-Bridge PWM Motor Driver

Features and Benefits

- 750 mA continuous output current
- 45 V output sustaining voltage
- Internal clamp diodes
- Internal PWM current control
- Low output saturation voltage
- Internal thermal shutdown circuitry
- Similar to dual PBL3717 or UC3770

Packages

Package B 24-pin Batwing DIP



Package LB 24-pin Batwing SOICW



Package EB 44-pin PLCC with internally-fused leads



Not to scale

Description

The UDx2916 motor drivers drive both windings of a bipolar stepper motor or bidirectionally control two DC motors. Both bridges are capable of sustaining 45 V and include internal pulse-width modulation (PWM) control of the output current to 750 mA. The outputs have been optimized for a low output saturation voltage drop (less than 1.8 V total source plus sink at 500 mA).

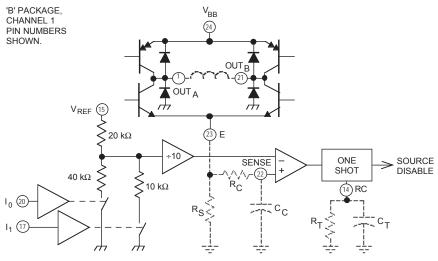
For PWM current control, the maximum output current is determined by user selection of a reference voltage and sensing resistor. Two logic-level inputs select output current limits of 0%, 33%, 67%, or 100% of the maximum level. A PHASE input to each bridge determines load current direction.

The bridges include both ground-clamp and flyback diodes for protection against inductive transients. Internally generated delays prevent crossover currents when switching current direction. Special power-up sequencing is not required. Thermal protection circuitry disables the outputs if the chip temperature exceeds safe operating limits.

The device is supplied in a 24-pin dual in-line plastic (DIP, package B) with two pairs of batwing leads as heat-sinkable tabs for enhanced power dissipation capabilities. The LB package is a 24-lead surface-mount wide SOIC with two pairs

 $Continued\ on\ the\ next\ page...$

PWM Current-Control Circuitry



Dwg. EP-007B

Description (continued)

of batwing leads. The EB package is a 44-lead power PLCC with 11 internally-fused leads on two sides. Their webbed-lead construction provides for maximum package power dissipation in the smallest possible construction.

The devices are available for operation from –20°C to 85°C (range N), and from –40°C to 105°C (range Q). All packages are lead (Pb) free, with 100% matte tin leadframe plating.

Selection Guide

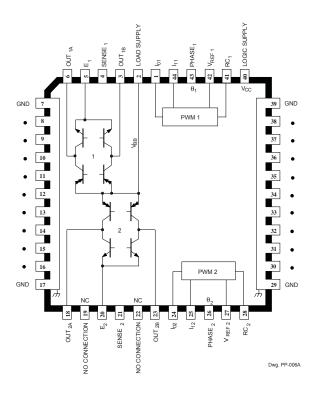
Part Number	Package	Packing	Ambient Temperature (°C)	
UDN2916B-T	24-pin batwing DIP	15 per tube		
UDN2916EB-T	44-pin internally fused lead PLCC	17 per tube		
UDN2916EBTR-T	44-pin internally fused lead PLCC 450 per reel		-20 to 85	
UDN2916LB-T	24-pin batwing SOICW	31 per tube		
UDN2916LBTR-T	24-pin batwing SOICW	1000 per reel		
UDQ2916B-T	24-pin batwing DIP	15 per tube		
UDQ2916EB-T	44-pin internally fused lead PLCC	17 per tube		
UDQ2916EBTR-T	44-pin internally fused lead PLCC	450 per reel	-40 to 105	
UDQ2916LB-T	Q2916LB-T 24-pin batwing SOICW			
UDQ2916LBTR-T	24-pin batwing SOICW	1000 per reel		

Absolute Maximum Ratings

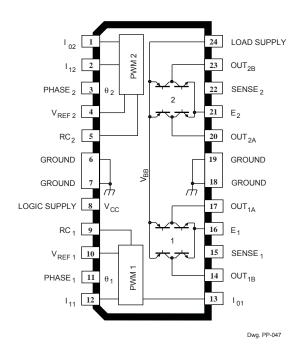
Characteristic	Symbol	Notes		Rating	Units
Motor Supply Voltage	V _{BB}			45	V
Logic Supply Voltage	V _{CC}			7.0	V
Input Voltage	V _{IN}			-0.3 to $V_{CC} + 0.3$	V
Output Emitter Voltage	V _E			1.5	V
Output Current*	la	Peak	Output current rating may be limited by duty cycle, ambient temperature, and heat sinking.	1.0	Α
	lout	Continuous	Under any set of conditions, do not exceed the specified current rating or T _J (max)	750	mA
Package Power Dissipation	P _D	See graph		_	W
On and the Archivest Towns and the	_	Range N		-20 to 85	°C
Operating Ambient Temperature	T _A	Range Q		-40 to 105	°C
Maximum Junction Temperature	T _J (max)			150	°C
Storage Temperature	T _{stg}			-55 to 150	°C



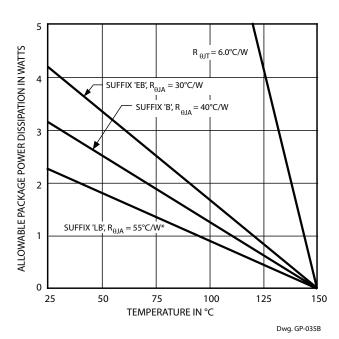
EB Package (PLCC)



LB Package (SOIC)

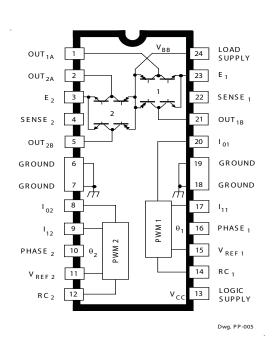


Power Dissipation



*Measured on a single-layer board, with 1 sq. in. of 2 oz copper area. For additional information, refer to the Allegro Web site.

B Package (DIP)



ELECTRICAL CHARACTERISTICS at T_A = +25°C, T_J \leq 150°C, V_{BB} = 45 V, V_{CC} = 4.75 V to 5.25 V, V_{REF} = 5.0 V (unless otherwise noted).

				Lim	its	
Characteristic	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Output Drivers (OUT _A or OUT _B)			•			
Motor Supply Range	V _{BB}		10		45	V
Output Leakage Current	ICEX	V _{OUT} = V _{BB}	_	< 1.0	50	μA
		V _{OUT} = 0	_	<-1.0	-50	μΑ
Output Sustaining Voltage	V _{CE(sus)} I _{OUT} = ±750 mA, L = 3.0 mH		45	_	_	V
Output Saturation Voltage	V _{CE(SAT)}	Sink Driver, I _{OUT} = +500 mA	_	0.4	0.6	V
		Sink Driver, I _{OUT} = +750 mA	_	1.0	1.2	V
		Source Driver, I _{OUT} = -500 mA	_	1.0	1.2	V
		Source Driver, I _{OUT} = -750 mA	_	1.3	1.5	V
Clamp Diode Leakage Current	I _R	V _R = 45 V	_	< 1.0	50	μA
Clamp Diode Forward Voltage	V _F	I _F = 750 mA	_	1.6	2.0	V
Driver Supply Current	I _{BB(ON)}	Both Bridges ON, No Load	_	20	25	mA
	I _{BB(OFF)}	Both Bridges OFF	_	5.0	10	mA
Control Logic						l
Input Voltage	V _{IN(1)}	All inputs	2.4	_	_	V
	V _{IN(0)}	All inputs	_	_	0.8	V
Input Current	I _{IN(1)}	V _{IN} = 2.4 V	_	<1.0	20	μA
		V _{IN} = 0.8 V	–	- 3.0	-200	μA
Reference Voltage Range	V _{REF}	Operating	1.5	_	7.5	V
Current Limit Threshold	V _{REF} /V _{SENSE}	I ₀ = I ₁ = 0.8 V	9.5	10	10.5	_
(at trip point)		I ₀ = 2.4 V, I ₁ = 0.8 V	13.5	15	16.5	_
		I ₀ = 0.8 V, I ₁ = 2.4 V	25.5	30	34.5	_
Thermal Shutdown Temperature	T _J		 -	170	_	°C
Total Logic Supply Current	I _{CC(ON)}	I ₀ = I ₁ = 0.8 V, No Load	-	40	50	mA
	I _{CC(OFF)}	I ₀ = I ₁ = 2.4 V, No Load	 	10	12	mA
Fixed Off-Time	t _{off}	R _T = 56 kΩ, C _T = 820 pF	_	46	_	μs



APPLICATIONS INFORMATION

PWM CURRENT CONTROL

The UDx2916 dual bridges drive both windings of a bipolar stepper motor. Output current is sensed and controlled independently in each bridge by an external sense resistor, $R_{\rm S}$, internal comparator, and monostable multivibrator.

When the bridge is turned on, current increases in the motor winding and it is sensed by the external sense resistor until the sense voltage, V_{SENSE} , reaches the level set at the comparator input:

$$I_{TRIP} = V_{REF}/10 R_S$$

The comparator then triggers the monostable, which turns off the source driver of the bridge.

The actual load current peak will be slightly higher than the trip point (especially for low-inductance loads) because of the internal logic and switching delays. This delay, $t_{\rm d}$, is typically 2 μs . After turn-off, the motor current decays, circulating through the ground-clamp diode and sink transistor. The source driver off-time (and therefore the magnitude of the current decrease) is determined by the external RC timing components of the monostable:

$$t_{off} = R_T C_T$$

where:

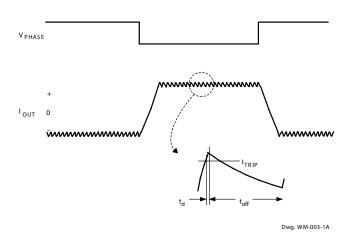
 $R_T = 20 \text{ to } 100 \text{ k}\Omega, \text{ and } C_T = 100 \text{ to } 1000 \text{ pF}.$

The fixed off-time should be short enough to keep the current chopping above the audible range (< 46 μ s) and long enough to properly regulate the current. Because only slow-decay current control is available, short off times (< 10 μ s) require additional efforts to ensure proper current regulation. Factors that can negatively affect the ability to properly regulate the current when using short off times include: higher motor-supply voltage, light load, and longer than necessary blank time.

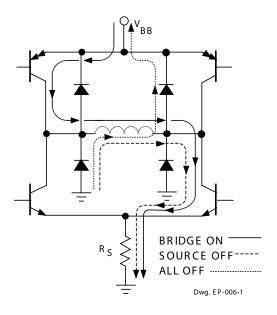
When the source driver is re-enabled, the winding current (the sense voltage) is again allowed to rise to the comparator's threshold. This cycle repeats itself, maintaining the average motor winding current at the desired level.

Loads with high distributed capacitances may result in high turn-on current peaks. This peak (appearing across $R_{\rm S})$ will attempt to trip the comparator, resulting in erroneous current control or high-frequency oscillations. An external $R_{\rm C}C_{\rm C}$ time delay should be used to further delay the action of the comparator. Depending on load type, many applications will not require these external components (SENSE connected to E).

PWM OUTPUT CURRENT WAVE FORM



LOAD CURRENT PATHS





LOGIC CONTROL OF OUTPUT CURRENT

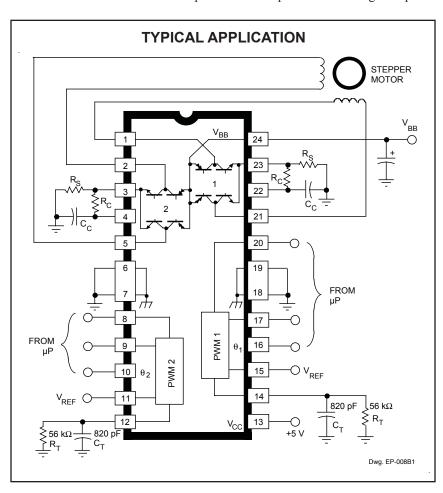
Two logic level inputs (I_0 and I_1) allow digital selection of the motor winding current at 100%, 67%, 33%, or 0% of the maximum level per the table. The 0% output current condition turns off all drivers in the bridge and can be used as an OUTPUT ENABLE function.

CURRENT-CONTROL TRUTH TABLE

I ₀	I ₁	Output Current
L	L	$V_{REF}/10 R_S = I_{TRIP}$
н	L	$V_{REF}/15 R_S = 2/3 I_{TRIP}$
L	Н	$V_{REF}/30 R_S = 1/3 I_{TRIP}$
Н	Н	0

These logic level inputs greatly enhance the implementation of microprocessor controlled drive formats.

During half-step operations, the I_0 and I_1 allow the microprocessor to control the motor at a constant torque between all positions in an eight-step se-



quence. This is accomplished by digitally selecting 100% drive current when only one phase is on and 67% drive current when two phases are on. Logic highs on both I_0 and I_1 turn-off all drivers to allow rapid current decay when switching phases. This helps to ensure proper motor operation at high step rates.

The logic control inputs can also be used to select a reduced current level (and reduced power dissipation) for "hold" conditions and/or increased current (and available torque) for start-up conditions.

GENERAL

The PHASE input to each bridge determines the direction motor winding current flows. An internally generated dead time (approximately 2 μs) prevents crossover currents that can occur when switching the PHASE input.

All four drivers in the bridge output can be turned-off between steps ($I_0 = I_1 \ge 2.4 \text{ V}$), resulting in a fast current decay through the internal output clamp and flyback diodes. The fast current decay is desirable in half-step and high-speed applications. The PHASE, I_0 , and I_1 inputs float high.

Varying the reference voltage, V_{REF} , provides continuous control of the peak load current for micro-stepping applications.

Thermal protection circuitry turns-off all drivers when the junction temperature reaches +170°C. It is only intended to protect the device from failures due to excessive junction temperature and should not imply that output short circuits are permitted. The output drivers are re-enabled when the junction temperature cools to +145°C.

The UDx2916 output drivers are optimized for low output saturation voltages—less than 1.8 V total (source plus sink) at 500 mA. Under normal operating conditions, when combined with the excellent thermal properties of the package designs, this allows continuous operation of both bridges simultaneously at 500 mA.

TRUTH TABLE

PHASE	OUTA	OUTB
Н	Н	L
L	L	Н



APPLICATION NOTES

Current Sensing

To minimize current sensing inaccuracies caused by ground trace IR drops, each current-sensing resistor should have a separate return to the ground terminal of the device. For low-value sense resistors, the IR drops in the PCB can be significant and should be taken into account. The use of sockets should be avoided as their contact resistance can cause variations in the effective value of $R_{\rm S}$.

Generally, larger values of R_S reduce the aforementioned effects but can result in excessive heating and power loss in the sense resistor. The selected value of R_S should not cause the absolute maximum voltage rating of 1.5 V, for the SENSE terminal, to be exceeded. The recommended value of R_S is in the range of:

$$R_{\rm S} = 0.75 / I_{\rm TRIP}({\rm max}) \pm 50\%$$
.

If desired, the reference input voltage can be filtered by placing a capacitor from REFIN to ground. The ground return for this capacitor as well as the bottom of any resistor divider used should be independent of the high-current power-ground trace to avoid changes in REFIN due to IR drops.

Thermal Considerations

For reliable operation, it is recommended that the maximum junction temperature be kept below 110°C to 125°C. The junction temperature can be measured best by attaching a thermocouple to the power tab or batwing of the device and measuring the tab temperature, T_{TAB} . The junction temperature can then be approximated by using the formula:

$$T_{\rm J} = T_{\rm TAB} + (2 \times I_{\rm LOAD} \times V_{\rm F} \times R_{\rm \theta JT})$$
,

where V_F can be chosen from the electrical specification table

for the given level of I_{LOAD} . The value for $R_{\theta JT}$ is approximately 6°C/W for both package styles.

The power dissipation of the batwing packages can be improved 20% to 30% by adding a section of printed circuit board copper (typically 6 to 18 square centimeters) connected to the batwing terminals of the device.

The thermal performance in applications that run at high load currents, high duty cycles, or both, can be improved by adding external diodes from each output to ground in parallel with the internal diodes. Fast-recovery (≤200 ns) diodes should be used to minimize switching losses.

Load Supply Terminal

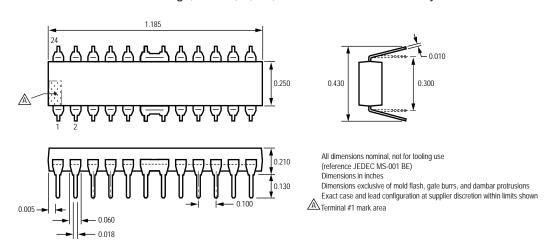
The load supply terminal, VBB, should be decoupled with an electrolytic capacitor (\geq 47 μ F is recommended), placed as close to the device as is physically practical. To minimize the effect of system ground IR drops on the logic and reference input signals, the system ground should have a low-resistance return to the load supply voltage.

Fixed Off-Time Selection

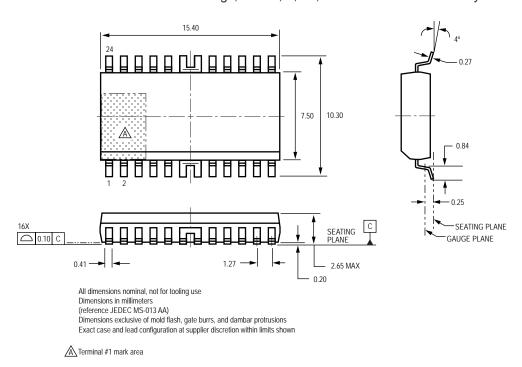
With increasing values of t_{OFF} , switching losses decrease, low-level load current regulation improves, EMI reduces, PWM frequency decreases, and ripple current increases. The value of t_{OFF} can be chosen for optimization of these parameters. For applications where audible noise is a concern, typical values of t_{OFF} should be chosen in the range of 15 to 35 μ s.



Package B, 24-pin DIP External batwings, Pins 6, 7, 18, and 19 are fused internally



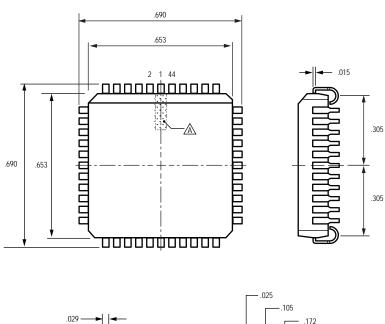
Package LB, 24-pin SOICW External batwings, Pins 6, 7, 18, and 19 are fused internally

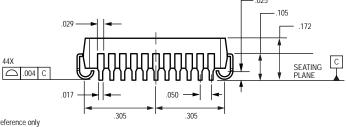




UDN2916EB

Package EB, 44-pin PLCC External batwings, Pins 7 through 17 and 29 through 39 are fused internally





Preliminary dimensions, for reference only (reference JEDEC MS-018 AC) Dimensions in inches

Millimeters (mm) in brackets, for reference only

Dimensions exclusive of mold flash, gate burrs, and dambar protrusions

Exact case and lead configuration at supplier discretion within limits shown

A Terminal #1 mark area

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